

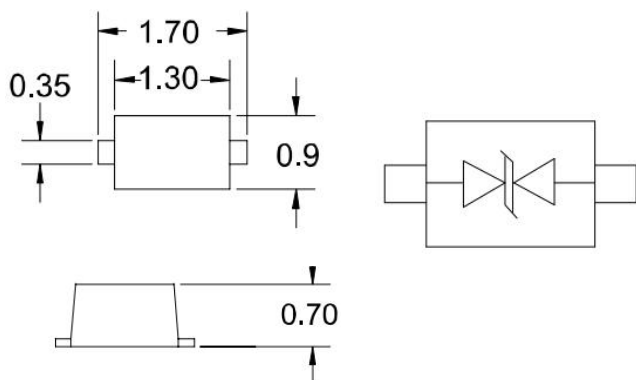
Description

The SD05CL is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, portable devices, digital cameras, power supplies and many other portable applications where board space comes at a premium. Also because of its low capacitance, it is suited for use in high frequency designs such as USB 2.0 high speed, VGA, DVI, SDI and other high speed line applications.

Features

- Protects one data line
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 15\text{kV}$
 - Contact discharge: $\pm 8\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
- RoHS Compliant

Dimensions & Symbol (Unit: mm Max)



Mechanical Characteristics

- Package: SOD-523
- Case Material: "Green" Molding Compound.
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- Audio Players
- Keypads, Side Keys, LCD Displays

Marking Information



Details marking code reference specification of approval list

Ordering Information

Part Number	Packaging	Reel Size
SD05CL	3000/Tape & Reel	7 inch

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p=8/20\mu\text{s}$ waveform)	P_{pp}	40	W
Peak Pulse Current (8/20 μs)	I_{pp}	2	A
ESD per IEC 61000-4-2 (Air)	V_{ESD}	± 15	kV
ESD per IEC 61000-4-2 (Contact)		± 8	
Operating Temperature Range	T_J	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V_{RWM}			5	V	
Breakdown Voltage	V_{BR}	6			V	$I_T = 1\text{mA}$
Reverse Leakage Current	I_R			0.15	μA	$V_{RWM}=5\text{V}$
Clamping Voltage	V_C			10	V	$I_{PP} = 1\text{A}$ (8 x 20 μs pulse)
Clamping Voltage	V_C			13	V	$I_{PP} = 2\text{A}$ (8 x 20 μs pulse)
Junction Capacitance	C_J		2.5	3.5	pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$

Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise Specified)

Figure 1: Peak Pulse Power Vs Pulse Time

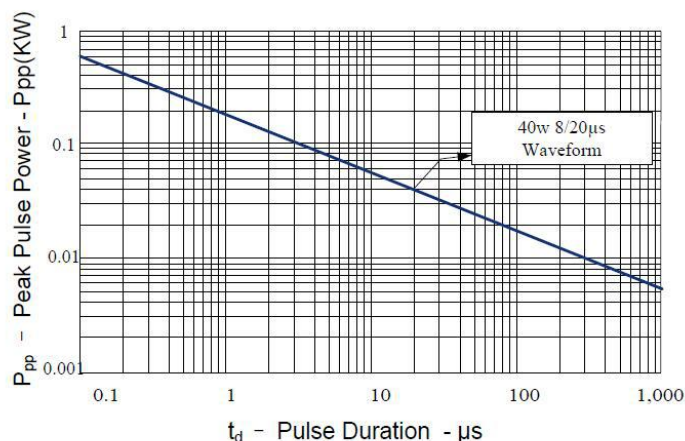


Figure 2: Power Derating Curve

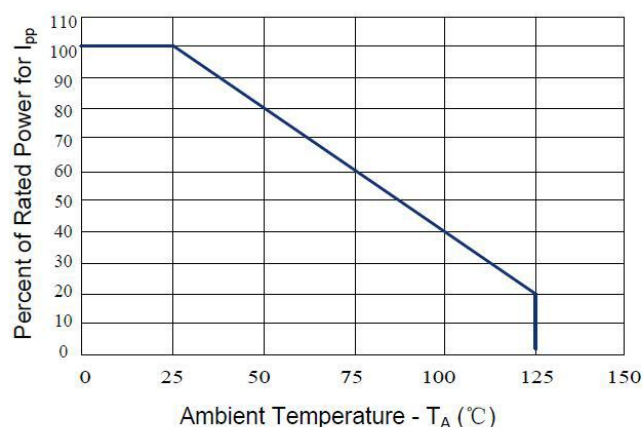


Figure 3: Clamping Voltage vs. Peak Pulse Current

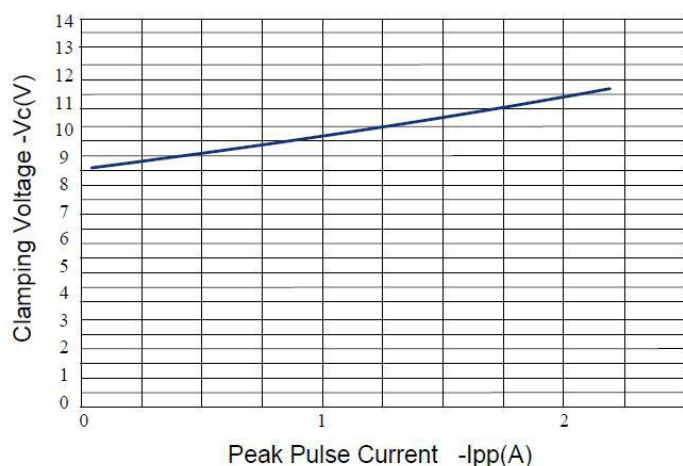


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

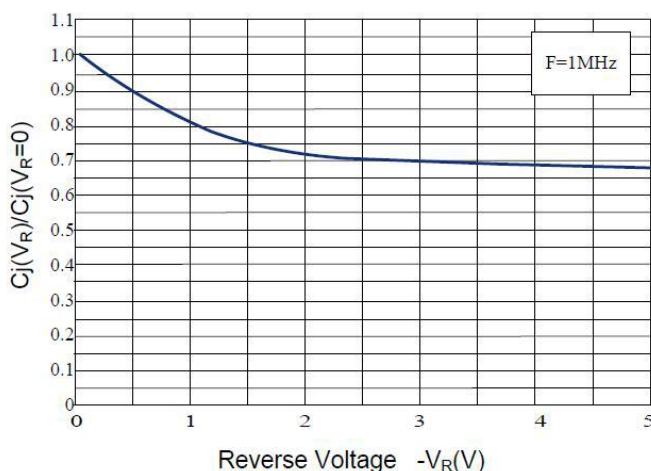
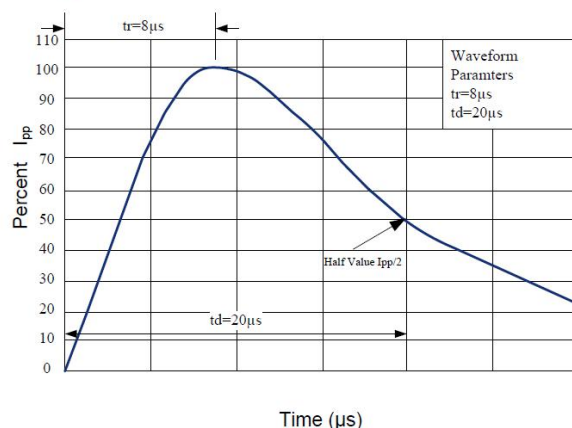
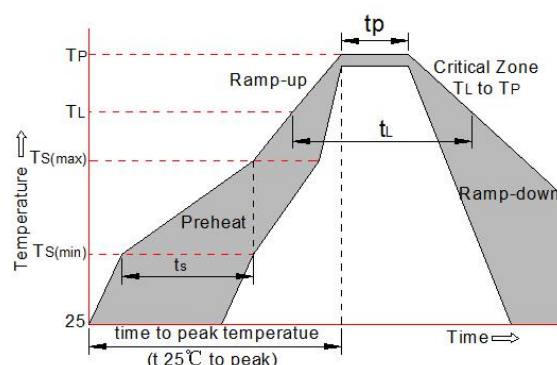


Figure 5: Pulse Waveform

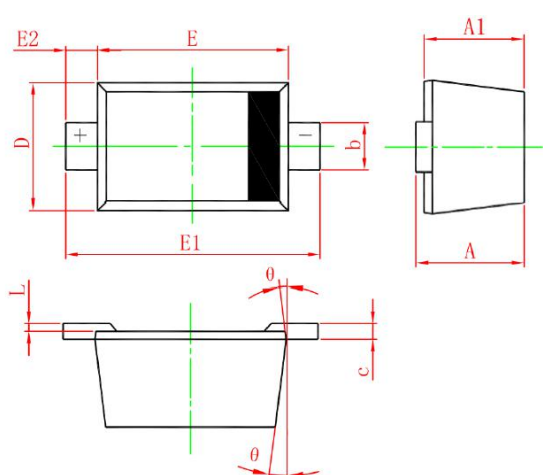


Soldering Parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Mechanical Data



SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.51	-	0.77	0.020	-	0.031
A1	0.50	-	0.70	0.020	-	0.028
b	0.25	-	0.35	0.010	-	0.014
c	0.08	-	0.15	0.003	-	0.006
D	0.75	-	0.85	0.030	-	0.033
E	1.10	-	1.30	0.043	-	0.051
E1	1.50	-	1.70	0.059	-	0.067
E2	0.20REF			0.008REF		
L	0.01	-	0.07	0.001	-	0.003
Φ	7° REF			7° REF		

Suggested Land Pattern

